

# ABSTRACT

In a wafer dicing/die bonding sheet comprising a  
5 backing member, an adhesive layer, and a protective member,  
the adhesive layer is made of an adhesive composition  
comprising a phenolic hydroxyl radical-bearing polyimide  
resin, an epoxy resin, and an epoxy resin curing agent, the  
ratio of the total weight of the epoxy resin and the epoxy  
10 resin curing agent to the weight of the polyimide resin being  
from 0.1:1 to 3:1. Due to heat resistance, improved adhesive  
properties and a low modulus of elasticity, the wafer  
dicing/die bonding sheet is effective for reducing the  
warpage of a chip after die bonding.